RoHS Pb **0603L SL Series** c UL us pending

Device Specification

ELECTRICAL CHARACTERISTICS

Part Number	I_{hold} (A)	I_{trip} (A)	V_{max} (Vdc)	I_{max} (A)	Pd_{max} (W)	Maximum Time-to-Trip		Resistance	
						Current (A)	Time (Sec.)	R_{min} (Ω)	R_{1max} (Ω)
0603L200SL	2.00	4.00	6	50	0.6	8.00	1.00	0.005	0.050

Note: I_{hold} = Hold current: maximum current device will pass without tripping in 20℃ still air.

I_{trip} = Trip Current: minimum current at which the device will trip in 20℃ still air.

V_{max} = Maximum voltage device can withstand without damage at rated current (Imax)

I_{max} = Maximum fault current device can withstand without damage at rated voltage (Vmax)

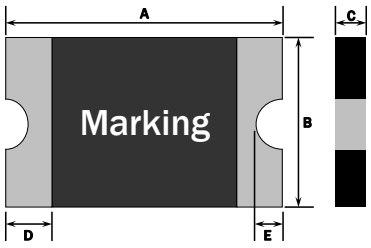
Pd = Power dissipated from device when in the tripped state at 20℃ still air.

R_{min} = Minimum resistance of device in initial (un-soldered) state.

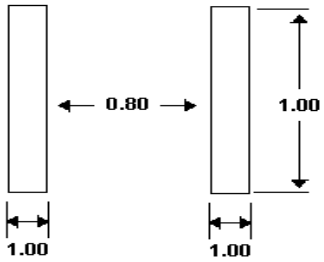
R_{1max} = Maximum resistance of device at 20℃ measured one hour after tripping or reflow soldering of 260℃ for 20 sec.

Caution :Operation beyond the specified rating may result in damage and possible arcing and flame.

Figure



Solder Pad Layout (mm)



PHYSICAL DIMENSIONS (mm)

Part Number	A		B		C		D		E	
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.
0603L200SL	1.40	1.80	0.60	1.00	0.40	1.00	0.15	0.50	-	0.40